



PCN / EOL Notification

Product Change Notification Number: SC070203

Date: January 16, 2007

Title: 2Mbit DataFlash Die Shrink / Full Conversion to RoHS & Green Compliant Packaging / CBGA, 28TSOP, 28SOIC, and CASON Package Obsolescence.

Product Identification:

AT45DB021B – All Packages

[See Attachment A](#)

Reason for Change:

- | | | |
|---|--|------------------------------------|
| <input checked="" type="checkbox"/> Design | <input checked="" type="checkbox"/> Processing | <input type="checkbox"/> Logistics |
| <input type="checkbox"/> Manufacturing Location | <input type="checkbox"/> Quality/Reliability | <input type="checkbox"/> Material |

Change Description:

The Atmel 2Mbit DataFlash has undergone a shrink from the current 0.25µm process to the 0.13µm process. The maximum operating frequency has been increased from 20Mhz to 66Mhz, and new features have been added. Pb based packages will no longer be offered; all package level components will be fully green (Pb and Halide free). These RoHS compliant devices are backward compatible to a Pb based soldering process. In addition, the low volume CBGA, 28-pin SOIC and the 28-pin TSOP packages will not be offered. **Board changes are REQUIRED.**

Identification Method to Distinguish Change:

The topside marking reflects the part number change to AT45DB021D-xx.

AT45DB021D-SU= 8-lead SOIC EIAJ (wide body) Industrial temperature (Green, RoHS compliant)

AT45DB021D-SSU= 8-lead SOIC Jedec (narrow body) Industrial temperature (Green, RoHS compliant)

AT45DB021D-MU= 8-pad MLF (narrow body) Industrial temperature (Green, RoHS compliant)

Qualification Data:

- | | | |
|---|--|---|
| <input checked="" type="checkbox"/> available | <input type="checkbox"/> will be available in WW | <input type="checkbox"/> not applicable |
|---|--|---|

Samples:

- | | | |
|---|--|---|
| <input checked="" type="checkbox"/> available | <input type="checkbox"/> will be available in WW | <input type="checkbox"/> not applicable |
|---|--|---|

Quantifiable Impact on Quality & Reliability:

None

Proposed First Ship Date*: April 15, 2007

Last Time Buy Date: July 15, 2007

Last Ship Date: January 15, 2008

*The Estimated Implementation Date is the forecasted date that a customer may expect to receive changed product. This is determined by the estimated date of inventory depletion on the PCN issue date. This may be affected by fluctuations in supply and demand. Consequently, although customers should be prepared to receive changed product on this date, Atmel will continue to ship pre-changed product until a time in which inventory has been depleted. This may result in pre-changed product being shipped to customers after this forecasted date.

Atmel Contact: pcnadm@atmel.com

Atmel will deem this change accepted unless specific conditions of acceptance are provided in writing within 30 days from the date of this notice. All correspondence must be sent to the Quality Contact e-mail address listed above.

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Attachment A

EOL Part Number	Replacement Part Number	Comments
AT45DB021B-CC	AT45DB021D- MU	Note 1
AT45DB021B-CI	AT45DB021D- MU	Note 1
AT45DB021B-CU	AT45DB021D- MU	Note 1
45DB021B-RC	AT45DB021D-SU or SSU	Note 3
45DB021B-RI	AT45DB021D-SU or SSU	Note 3
45DB021B-RU	AT45DB021D-SU or SSU	Note 3
AT45DB021B-SC	AT45DB021D-SU	
AT45DB021B-SI	AT45DB021D-SU	
AT45DB021B-SJ	AT45DB021D-SU	
AT45DB021B-SU	AT45DB021D-SU	
AT45DB021B-TC	AT45DB021D-SSU or MU	Note 2
AT45DB021B-TI	AT45DB021D-SSU or MU	Note 2
AT45DB021B-TU	AT45DB021D-SSU or MU	Note 2
Not Previously Offered	AT45DB021D-SSU	Note 3
Not Previously Offered	AT45DB021D-MU	

Note 1: Atmel recommends the 8-pad MLF package as a leadless small form factor alternative. Board change is required.

Note 2: Atmel recommends the 8-pin SSU or MU for low Z height applications. Board change is required.

Note 3: Atmel recommends the 8-pin SSU or SU for long term footprint migration path. Board change is required.